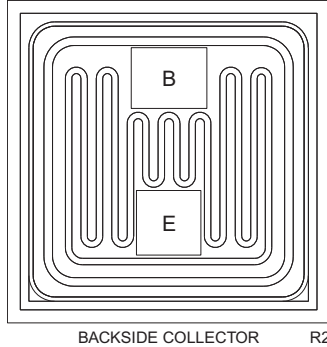


CP710V-CJD350

PNP - High Voltage Transistor Die

The CP710V-CJD350 is a silicon PNP transistor designed for high voltage applications.



MECHANICAL SPECIFICATIONS:

Die Size	26 x 26 MILS
Die Thickness	9.0 MILS
Base Bonding Pad Size	6.1 x 4.9 MILS
Emitter Bonding Pad Size	5.2 x 5.2 MILS
Top Side Metalization	Al – 30,000Å
Back Side Metalization	Au – 18,000Å
Scribe Alley Width	2.2 MILS
Wafer Diameter	5 INCHES
Gross Die Per Wafer	25,214

MAXIMUM RATINGS: (T_A=25°C)

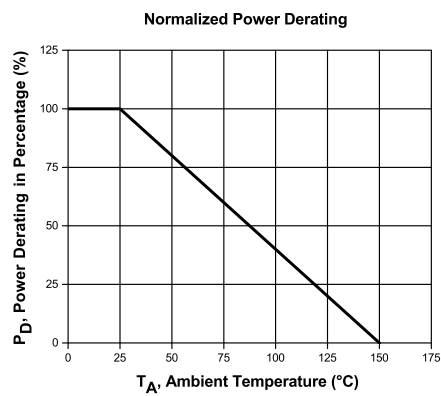
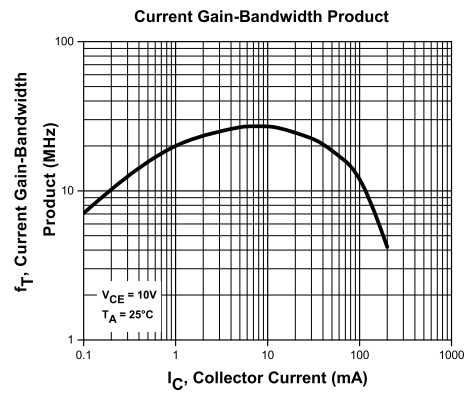
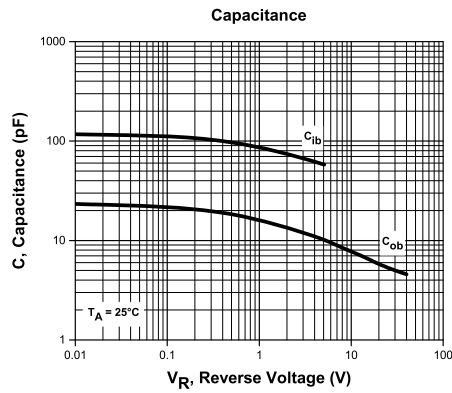
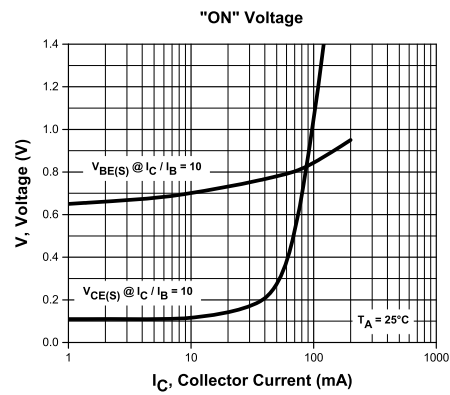
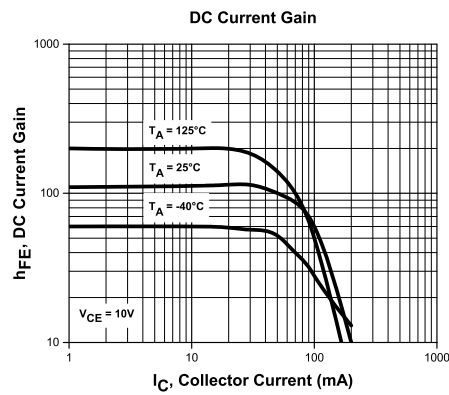
	SYMBOL		UNITS
Collector-Base Voltage	V _{CBO}	300	V
Collector-Emitter Voltage	V _{CEO}	300	V
Emitter-Base Voltage	V _{EBO}	3.0	V
Continuous Collector Current	I _C	500	mA
Peak Collector Current	I _{CM}	750	mA
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +150	°C

ELECTRICAL CHARACTERISTICS: (T_A=25°C)

SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
I _{CBO}	V _{CB} =300V		100	μA
I _{CEO}	V _{CE} =300V		100	μA
I _{EBO}	V _{EB} =3.0V		100	μA
BV _{CEO}	I _C =1.0mA	300		V
V _{CE(SAT)}	I _C =100mA, I _B =10mA		2.6	V
V _{BE(ON)}	V _{CE} =10V, I _C =1.0A		2.0	V
h _{FE}	V _{CE} =10V, I _C =50mA	30	240	
f _T	V _{CE} =10V, I _C =50mA, f=10MHz	10		MHz

CP710V-CJD350

Typical Electrical Characteristics



BARE DIE PACKING OPTIONS



BARE DIE IN TRAY (WAFFLE) PACK

CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-PART NUMBER-CM)



UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring,
100% tested with reject die inked.
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:
www.centrasemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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